

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A device for moulding foodstuff masses, comprising:

- a mould (14) provided with a plurality of sockets (16) which define respective pouring cavities;
- at least one insert (22) made of thermally conductive material associated, in a heat-exchange relationship, with said pouring cavity (16);
- at least one thermal-conditioning unit (24), associated to said insert made of thermally conductive material (2);
- a conveying structure (12,13) for moving a plurality of said moulds (14) along a path of movement; and
- a control unit (34) for generating control signals of said thermal-conditioning unit (24) according to a cycle (100 to 126) selectively predetermined for the thermal treatment of the material undergoing moulding in the course of the advance along said path,

wherein said mould (14) has electrical contact elements (28) which emerge on the outer surface of the mould (14) itself for the electrical supply of said at least one thermal-conditioning unit (24) and said electrical contact elements (28) have a slider conformation, so as to enable the electrical supply of said at least one conditioning unit (24) during movement of said mould (14) along a path of movement.

2. (Original) The device according to Claim 1, characterized in that said at least one insert (22) made of thermally conductive material defines at least part of the surface of said pouring cavity (16).

3. (Previously Presented) The device according to Claim 1, characterized in that said thermal-conditioning unit (24) is a refrigerating unit.

4. (Previously Presented) The device according to Claim 1, characterized in that said thermal-conditioning unit (24) is a Peltier cell.

5. (Previously Presented) The device according to Claim 1, characterized in that said thermal-conditioning unit (24) is stably associated to said mould (14).

6. (Original) The device according to Claim 5, characterized in that said thermal-conditioning unit (24) is incorporated in said mould (14).

7. (Previously Presented) The device according to Claim 1, characterized in that said mould (14) has a body made of thermally insulating material.

8. (Cancelled).

9. (Cancelled).

10. (Previously Presented) The device according to Claim 1, characterized in that at least some of the sockets (16) of said plurality have associated thereto an insert made of thermally conductive material (22) common to a number of sockets (16).

11. (Previously Presented) The device according to Claim 1, characterized in that at least one set of sockets (16) of said plurality has associated thereto thermal-conditioning units (24) that are distinct from one another.

12. (Previously Presented) The device according to Claim 1, characterized in that at least some sockets (16) of said plurality have associated thereto a thermal-conditioning unit (24) common to a number of sockets (16).

13. (Previously Presented) The device according to Claim 1, characterized in that said mould (14) has contact elements (28) which emerge on the outer surface of the mould (14) itself for the electrical supply of said at least one thermal-conditioning unit (24).

14. (Cancelled).

15. (Cancelled).

16. (Previously Presented) The device according to Claim 1, characterized in that said conveying structure comprises drawing elements (12) at least in part configured as lines for the electrical supply of said at least one thermal-conditioning unit (24) through said contact elements (28).

17. (Cancelled)

18. (Previously Presented) The device according to Claim 1, characterized in that said mould (14) carries associated thereto a processing unit (32) for controlling operation of said at least one thermal-conditioning unit (24).

19. (Original) The device according to Claim 18, characterized in that said processing unit (32) is stably associated to said mould (14).

20. (Original) The device according to Claim 19, characterized in that said processing unit (32) is incorporated in said mould (14).

21. (Previously Presented) The device according to Claim 18, characterized in that said processing unit (32) is a microprocessor, a microcontroller, or else a processing unit for smart cards.

22. (Previously Presented) The device according to Claim 1, further comprising:

a processing unit (32) associated to said at least one mould (14) for controlling operation of said at least one thermal-conditioning unit (24); and

a line (12) for the transfer of said control signals from said control unit (34) to said processing unit (32) associated to said at least one mould (14).

23. (Original) The device according to Claim 22, characterized in that it comprises a plurality of said moulds (14) and in that said control unit (34) is configured for transmitting encoded signals to the processing units (32) associated to the moulds (14) of said plurality, said encoding identifying selectively the mould (14) of said plurality to which a given control signal is sent.

24. (Previously Presented) The device according to Claim 22, further comprising:

a conveying structure (12, 13) for moving said mould (14) along a path of movement, wherein said line (12) coincides, at least in part, with said conveying structure.